

ABS08-E

**SINGLE PHASE GLASS PASSIVATED
SURFACE MOUNT FLAT BRIDGE RECTIFIER
VOLTAGE: 800V CURRENT: 1.0A**

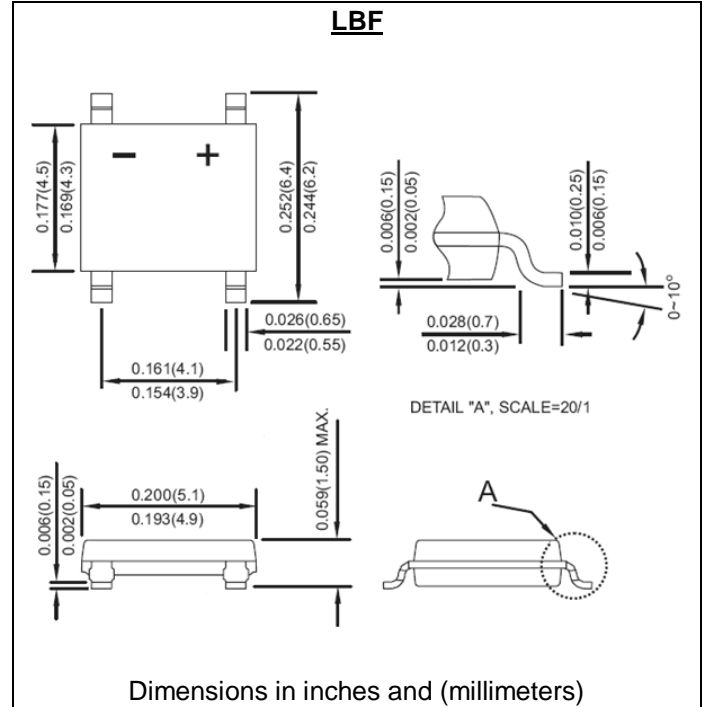


FEATURE

- Ideal for printed circuit board
- Glass passivated chip
- Reliable low cost construction utilizing molded plastic technique
- Small size, simple installation
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen Free

MECHANICAL DATA

- Terminal: Plated leads solderable per J-STD-002
- Case: UL-94 Class V-0 recognized Halogen Free Epoxy
- Polarity: Polarity symbol marked on body
- Marking: ABS10



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half -wave, 60Hz, resistive or inductive load rating at 25°C, unless otherwise stated)

	Symbol	ABS08-E	Units
Maximum Recurrent Peak Reverse Voltage	V _{rrm}	800	V
Maximum RMS Voltage	V _{rms}	560	V
Maximum DC blocking Voltage	V _{DC}	800	V
Maximum Average Forward Rectified Current on aluminum substrate on glass-epoxy P.C.B.	I _{f(av)}	1.0 0.8	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I _{fsm}	30	A
Rating for fusing(t<8.3ms)	I ² t	3.74	A ² sec
Maximum Instantaneous Forward Voltage at Forward Current 0.4A	V _f	0.95	V
Maximum DC Reverse Current at rated DC blocking voltage	I _r	5.0 100.0	μA
Typical Thermal resistance junction to lead on aluminum substrate on glass-epoxy P.C.B.	R _{th(jl)} R _{th(ja)}	42 69 88	°C/W
Storage and Operating Junction Temperature Range	T _{stg} , T _j	-55 to +150	°C

Note:

RATINGS AND CHARACTERISTIC CURVES ABS08-E

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

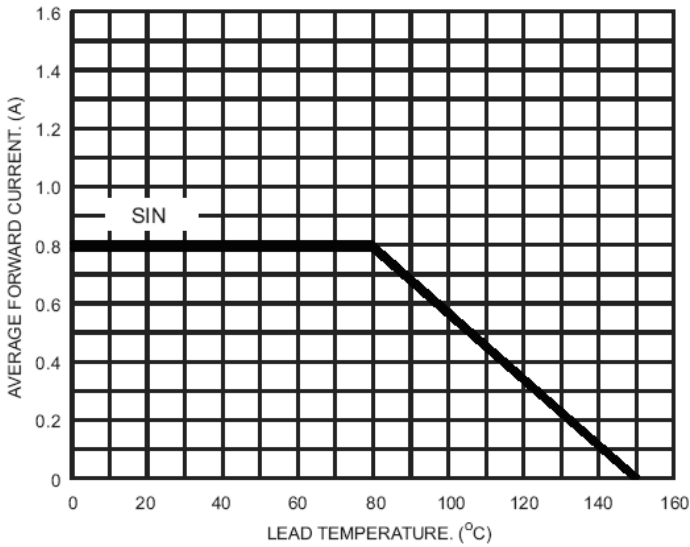


FIG.2- TYPICAL FORWARD CHARACTERISTICS

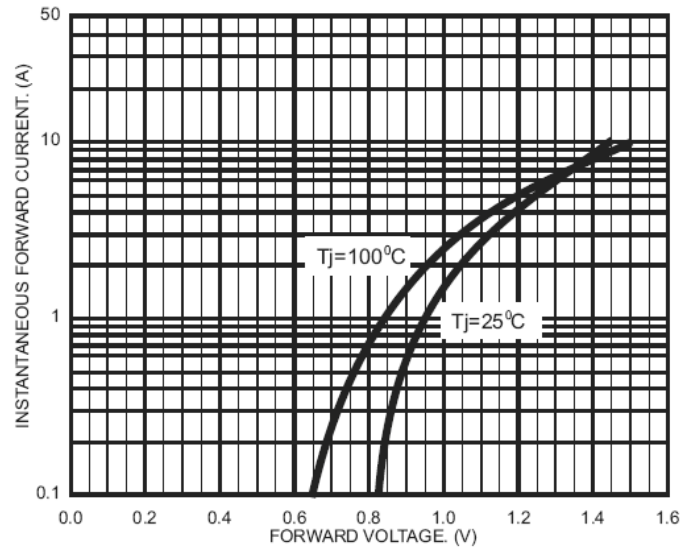


FIG.3- MAXIMUM FORWARD CURRENT DERATING CURVE

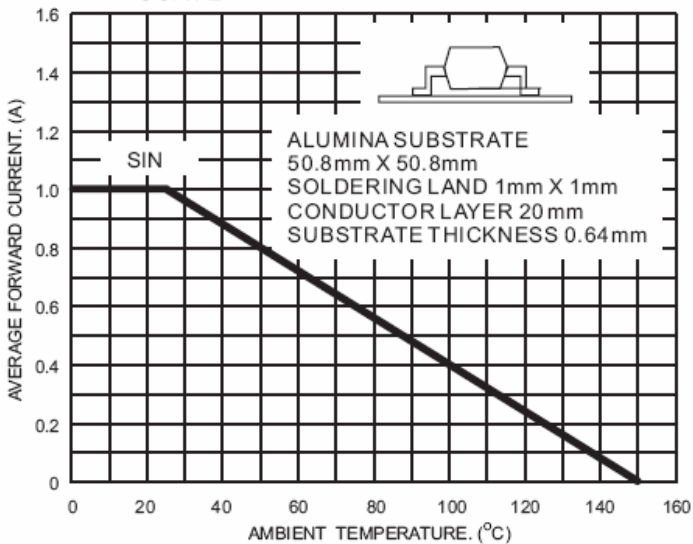


FIG.4- FORWARD POWER DISSIPATION

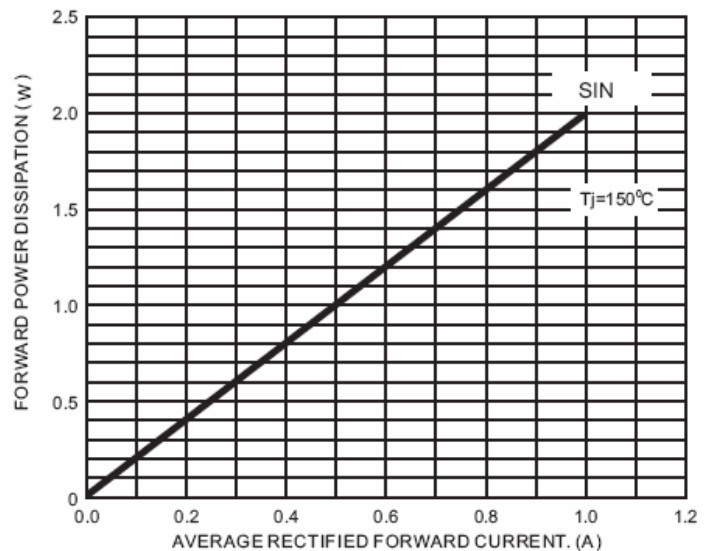


FIG.5- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

